

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L2	3	("6081031" "6555899" "6677672").PN. OR ("6734044"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L3	3987	(257/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/12 21:47
L4	385	L3 and (multi near2 layer multilayer laminate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L5	11	("5,196,725", "5,237,202", "5,399, 809", "5,734,198" "5,777,265").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L6	22	("4320438" "4839717" "4879588" "4891687" "4972253" "4980034" "5008734" "5012386" "5158912" "5235209" "5235211" "5258575" "5264729" "5272590" "5311057" "5331511").PN. OR ("5777265"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L7	25	(Multi near2 layer with lead near2 frame).ti. and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L8	9	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN. OR ("5389816"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L9	6	("4891687" "5089878" "5196725" "5214845" "5220195" "5237202").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L10	35	("4445271" "4835120" "4891687" "5032895" "5053921" "5089878" "5089881").PN. OR ("5220195"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L11	9	(US-5777265-\$ or US-5734198-\$ or US-5399809-\$ or US-5864173-\$ or US-5214845-\$ or US-4891687-\$ or US-5389816-\$).did. or (US-5777265-\$ or JP-04286148-\$). did.	USPAT; DERWENT	OR	ON	2005/12/12 21:47

L12	1	1992-386699.NRAN.	DERWENT	OR	ON	2005/12/12 21:47
L13	2	"5191725".pn.	USPAT; DERWENT	OR	ON	2005/12/12 21:47
L14	3	"5196725".pn.	USPAT; DERWENT	OR	ON	2005/12/12 21:47
L15	2	"5229647".pn.	USPAT; DERWENT	OR	ON	2005/12/12 21:47
L16	3	"5196725".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L17	2	"6734044".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L18	2	L17 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L19	2255	(IC chip integrated near2 circuit die semiconductor) near L17 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L20	197	L19 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L21	2255	(IC chip integrated near2 circuit die semiconductor) near L17 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L22	126	L20 and "257"\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L23	87	L20 and "257"\$.ccls.	USPAT	OR	ON	2005/12/12 21:47
L24	205	L19 and "257"\$.ccls.	USPAT	OR	ON	2005/12/12 21:47

L25	87	L24 and lead near2 frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L26	38	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) with lead	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L27	24	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) same lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L28	49	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium tungsten gold) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L29	34	L28 not "44"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L30	25	L28 not L27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L31	71	(IC chip integrated near2 circuit die semiconductor) near3 coated with (titanium it tungsten w gold au) and lead with frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L32	47	L31 not L27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L33	9	("3597834" "3848077" "4113981" "4925024" "5025114" "5180888" "5183969" "5262226").PN. OR ("5399809").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L34	138	("3784883" "4168507" "4541035" "4577214" "4595945" "4608592" "4639760" "4675717" "4680613" "4705917").PN. OR ("4891687").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47

L35	1317	laminat\$3 with lead adj frame	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L36	121	L35 and 257/66\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L37	138	L35 and 257/67\$1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L38	55	L36 and L37	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L39	204	L36 or L37	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L40	2	"6255141".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/12 21:47
L41	3	("3784948" "3925801" "4627151").PN. OR ("6255141"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L42	137	multi\$3layer near2 lead adj frame	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L43	132	L42 not L37	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L44	8	L42 and (solder adj contact solder near ball bump c4)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L45	1	"6734044".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47
L46	3	("6081031" "6555899" "6677672").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/12 21:47